

In the Claims

Cancel claims 11-25, without prejudice.

1 1. (Previously amended) A method for removing contaminate particulate matter from
2 a contaminate particle containing substrate surface comprising the steps of:
3 applying a sacrificial coating of a material to a substrate surface containing undesirable
4 particulate matter thereon, which material is to encapsulate and suspend the
5 undesirable particles therein;
6 fluidizing the material if necessary;
7 applying energy to the coated substrate to dislodge at least some of the particulate
8 matter from the surface of the substrate into the fluid sacrificial coating such that
9 the particulate matter is partially or fully encapsulated and suspended within the
10 sacrificial coating forming a particulate matter containing sacrificial material
11 coating;
12 forming the fluidized particulate matter containing sacrificial material coating into a
13 strippable film; and
14 removing the particulate matter containing sacrificial material coating strippable film
15 from the substrate surface providing a substrate surface having less particulate
16 matter thereon.

1 2. (original) The method of claim 1 wherein the substrate is a semiconductor wafer.

1 3. (original) The method of claim 1 wherein the sacrificial coating material is a fluid.

1 4. (original) The method of claim 1 wherein the energy used is sonic energy.

1 5. (original) The method of claim 1 wherein the energy used is thermal, centrifugal,
2 magnetic or vibrational.

1 6. (original) The method of claim 1 wherein the sacrificial coating material is a
2 liquid.

1 7. (original) The method of claim 1 wherein the sacrificial coating material is a
2 curable polymer.

1 8.-9. (canceled)

1 10. (original) The method of claim 1 wherein the material is a gas, liquid, vapor or
2 fluid polymer.

1 11.-25. (Canceled)

- 1 26. (Previously added) The method of claim 1 wherein the strippable film is formed
- 2 simultaneously with application of the energy to dislodge the particles.